



# P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)		
- 30	$0.0088$ at $V_{GS} = -10 \text{ V}$	- 19.2	44.8 nC		
- 30	0.0153 at V <sub>GS</sub> = -4.5 V	- 14.6	44.6110		

# SO-8 S 1 8 D S 2 7 D S 3 6 D Top View

#### **FEATURES**

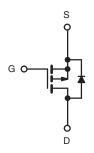
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

# ROHS COMPLIANT HALOGEN

FREE

## **APPLICATIONS**

Adaptor Switch



P-Channel MOSFET

Ordering Information: Si4483ADY-T1-0	3 (Lead (Pb)-free	and Halogen-free)
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Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	- 30	V	
Gate-Source Voltage		V <sub>GS</sub>	± 25	v	
	T <sub>C</sub> = 25 °C		- 19.2		
Continuous Drain Current (T = 150 °C)	T <sub>C</sub> = 70 °C		- 15.4		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 13.5 <sup>a, b</sup>		
	T <sub>A</sub> = 70 °C		- 10.9 <sup>a, b</sup>		
Pulsed Drain Current	I <sub>DM</sub>	- 70	A		
Continuous Course Dunin Diado Current	T <sub>C</sub> = 25 °C		- 4.9		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	- I <sub>S</sub>	- 2.4 <sup>a, b</sup>		
Avalanche Current		I <sub>AS</sub>	20		
Single-Pulse Avalanche Energy L = 0.1 mH		E <sub>AS</sub>	20	mJ	
	T <sub>C</sub> = 25 °C		5.9		
	T <sub>C</sub> = 70 °C		3.8	14/	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.9 <sup>a, b</sup>	W	
	T <sub>A</sub> = 70 °C		1.9 <sup>a, b</sup>		
Operating Junction and Storage Temperature Rang	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 10 s	R <sub>thJA</sub>	33	42	°C/W	
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	16	21	C/VV	

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s
- c. Maximum under steady state conditions is 85 °C/W.
- d. Based on  $T_C$  = 25 °C.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050 v.A		- 30		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = -250  \mu A$		5.3			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.2	- 2.1	- 2.6	٧	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA	
Zara Cata Valta na Duain Comunit		V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V			- 1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ = - 30 V, $V_{GS}$ = 0 V, $T_{J}$ = 55 °C			- 5		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
5	0	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 10 A		0.0073	0.0088	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = -4.5 \text{ V}, I_D = -7 \text{ A}$		0.0127	0.0153		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 10 A		32		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			3900			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		715		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			645			
Tatal Cata Charma	Qg	V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 10 A		90	135	nC	
Total Gate Charge				44.8	68		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -10 \text{ A}$		12.2			
Gate-Drain Charge	$Q_{gd}$			21.7			
Gate Resistance	$R_{g}$	f = 1 MHz	0.4	1.8	3.6	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			14	28		
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 15 V, $R_L$ = 1.5 $\Omega$		13	25	1	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D\cong$ - 10 A, $V_{GEN}=$ - 10 V, $R_g=$ 1 $\Omega$		49	90		
Fall Time	t <sub>f</sub>			13	25		
Turn-On Delay Time	t <sub>d(on)</sub>			70	120	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 15 V, $R_L$ = 1.5 $\Omega$		150	280		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D\cong$ - 10 A, $V_{GEN}=$ - 4.5 V, $R_g=$ 1 $\Omega$		43	80		
Fall Time	t <sub>f</sub>			28	55		
<b>Drain-Source Body Diode Characteris</b>	tics						
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 4.9	۸	
Pulse Diode Forward Current	I <sub>SM</sub>				- 70	A	
Body Diode Voltage	$V_{SD}$	$I_S = -3 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.72	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			41	70	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	10 A dl/dt 100 A/: T 05 00		41	70	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		18			
everse Recovery Rise Time t <sub>b</sub>			23		ns		

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

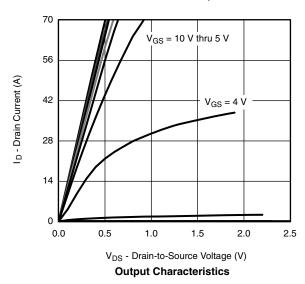
a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

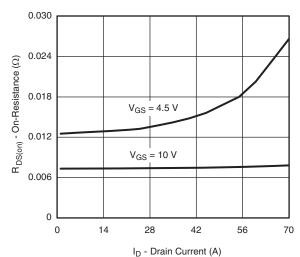
b. Guaranteed by design, not subject to production testing.



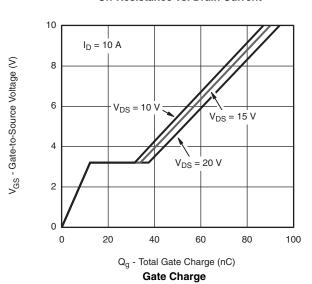


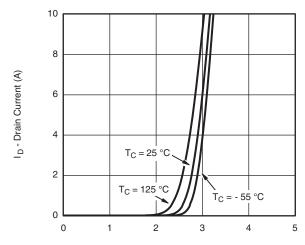
# TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



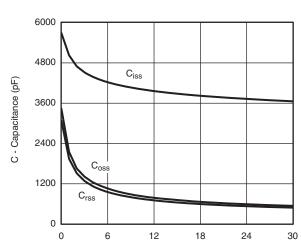


On-Resistance vs. Drain Current

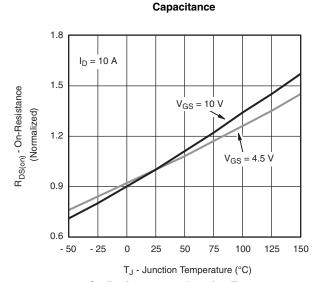




V<sub>GS</sub> - Gate-to-Source Voltage (V) **Transfer Characteristics** 



V<sub>DS</sub> - Drain-to-Source Voltage (V)

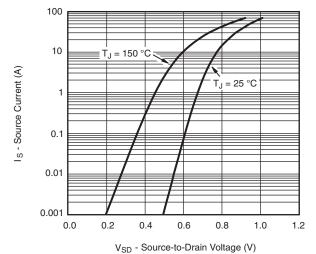


On-Resistance vs. Junction Temperature

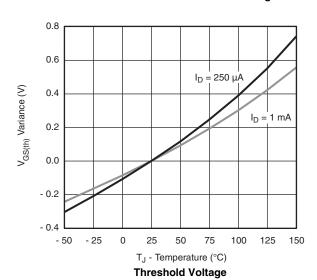
# Vishay Siliconix

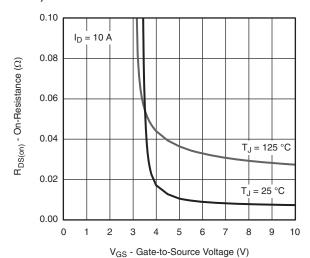
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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

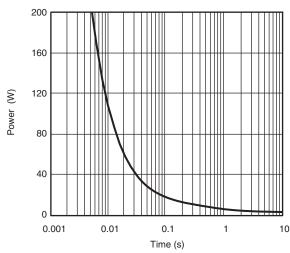


Source-Drain Diode Forward Voltage

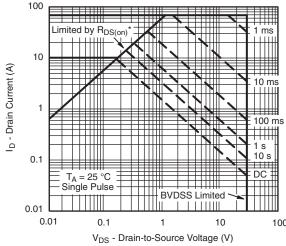




On-Resistance vs. Gate-to-Source Voltage



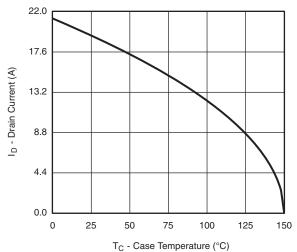
Single Pulse Power, Junction-to-Ambient



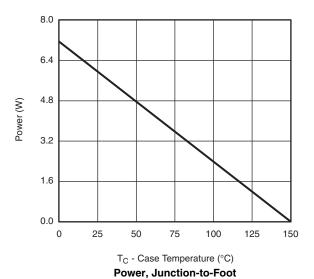
\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

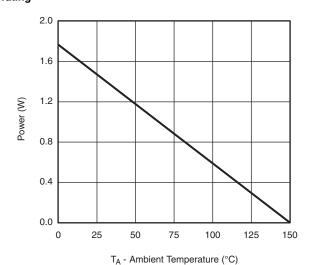


## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating\*





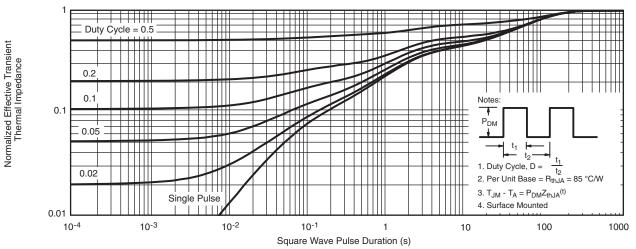
Power Derating, Junction-to-Ambient

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

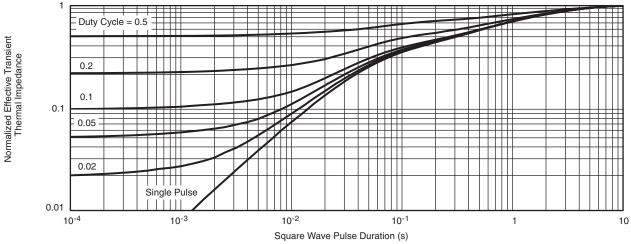
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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?68982">www.vishay.com/ppg?68982</a>.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIMETERS INCHES			HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A <sub>1</sub>	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



## **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

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